The Top Assisting Partner in the AI Supply Chain

Empowering the success of clients across different ecosystems through high-level collaboration

C SUN 志聖工業

2026 Q1 Investor's meeting

Yuanta Q1 Investment Forum

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward-looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design in, time to market, market competition, industrial cyclicality, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations. global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward-looking statements. Except as required by law. C Sun undertakes no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

G2C+
T STRATEGY ALLIANCE

G2C+ Alliance: The Platform Advantage

Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)

Thermal (熱)
Wet Process (濕製程)
UV/Plasma (光/電漿)

1,800+
聯盟總人數
(Total Alliance Workforce)

>600
研發人員
(R&D Personnel)

AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

Die Attach (黏晶)
Chip Sorter (揀晶)

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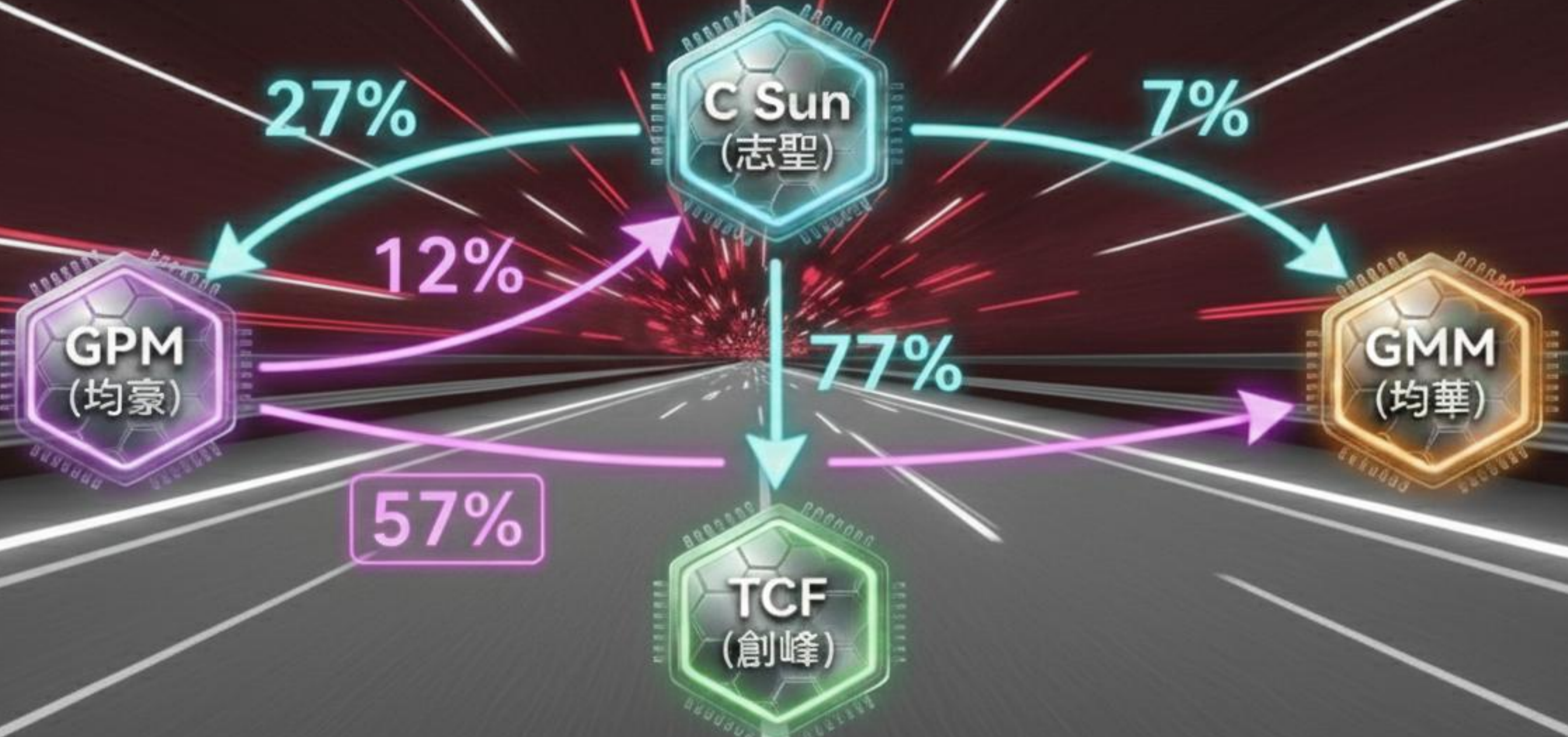
Cross Holding Structure



GPM = 均豪 ｜ GMM = 均華 ｜ C Sun = 志聖

Professional Collaborative Team on the AI Track

Continuous Recognition from Champion Team

2023:
Excellent Production Support
(卓越量產支援)

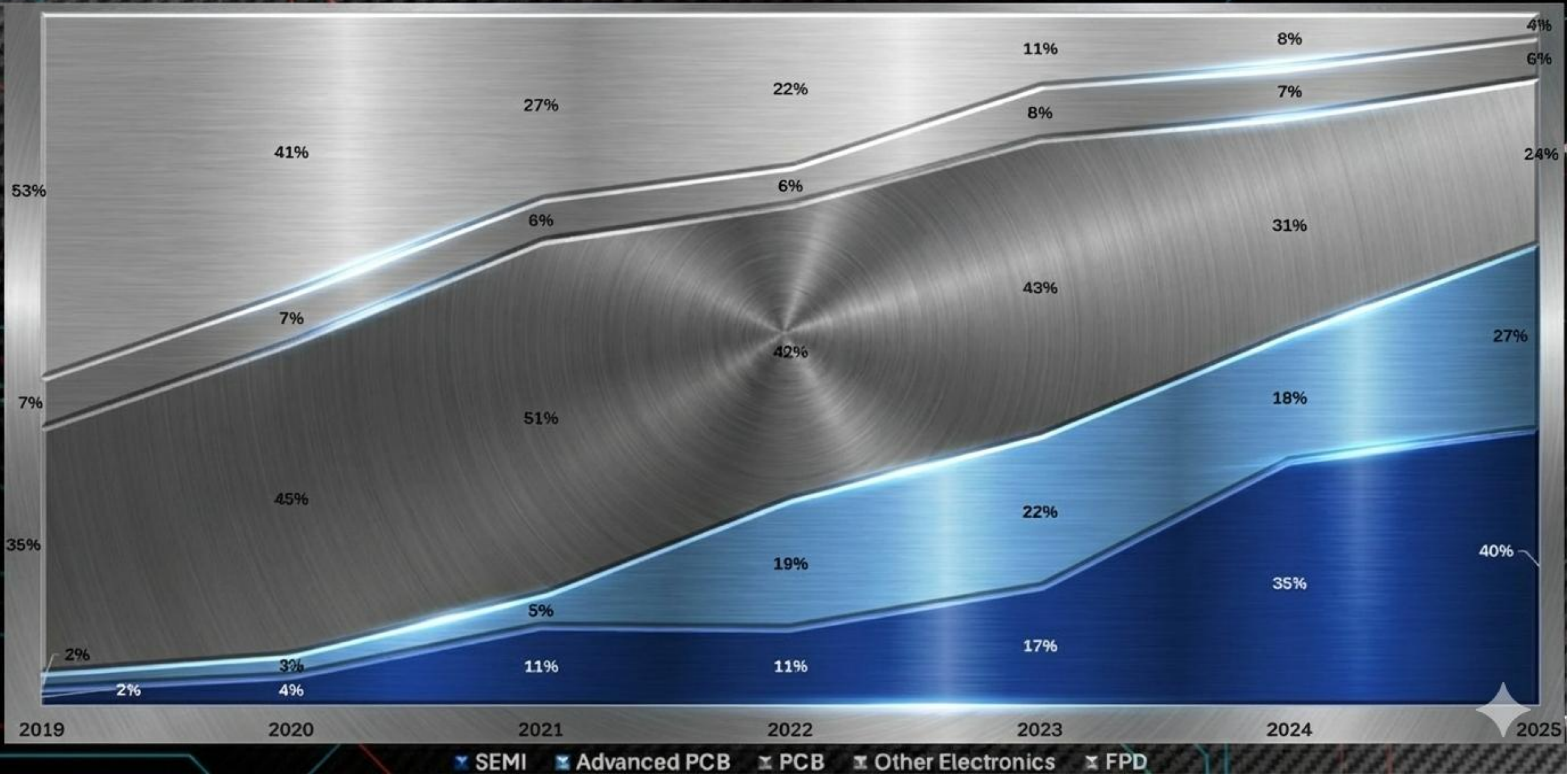
2024:
Outstanding Improvement
(傑出持續改善)

2025:
Excellent Production Support
(卓越量產支援)

Financial Review

Selected Items from Statements of Comprehensive Income (In NT$ millions unless otherwise noted)	2026 Jan	2025	4Q25	3Q25	1H25	2024	4Q25 QoQ	2025 YoY
Revenue-Consolidated	994	6,102	1,747	1,536	2,819	4,818	13.7%	26.6%
Gross Margin%		**43.3%**	**44.1%**	**44.2%**	**42.3%**	**41.2%**	**-0.1ppts**	**+2.1ppts**
Operating Expense		(1,760)	(493)	(526)	(741)	(1,347)	-6.3%	30.7%
Operating Expense%		**28.9%**	**28.2%**	**34.3%**	**30.5%**	**28.0%**	**-2.3ppts**	**+0.9ppts**
RD Expense		(543)	(170)	(164)	(208)	(362)	3.9%	49.8%
RD Expense %		**8.9%**	**9.8%**	**10.7%**	**7.4%**	**7.5%**	**-0.9ppts**	**+1.4ppts**
Operating Margin%		**14.5%**	**15.9%**	**10.0%**	**16.1%**	**13.2%**	**+5.9ppts**	**+1.3ppts**
Non-Operating Items		243	56	134	54	344	-58.4%	-29.1%
Net Income Attributable to Shareholders of the Parent Company		830	260	212	358	719	23.1%	15.4%
Net Profit Margin%		**13.6%**	**14.9%**	**13.8%**	**12.7%**	**14.9%**	**+1.1ppts**	**-1.3ppts**
EPS (NT$D)		5.5	1.72	1.4	2.38	4.8	22.9%	14.6%

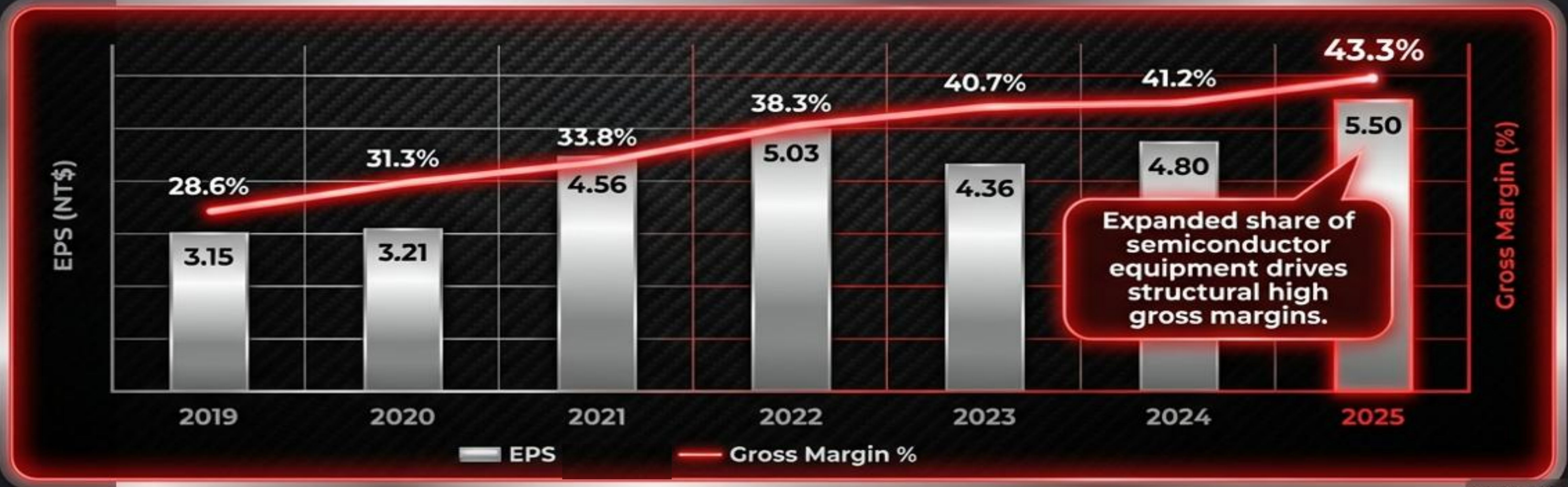
Revenue Composition



2025 Financial Highlights: Structural Transformation & Record Highs

2025 Revenue
NT$ 6.1 Billion
Record High

2025 EPS
NT$ 5.50



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2026 Opening: Record-High Single-Month Revenue

994

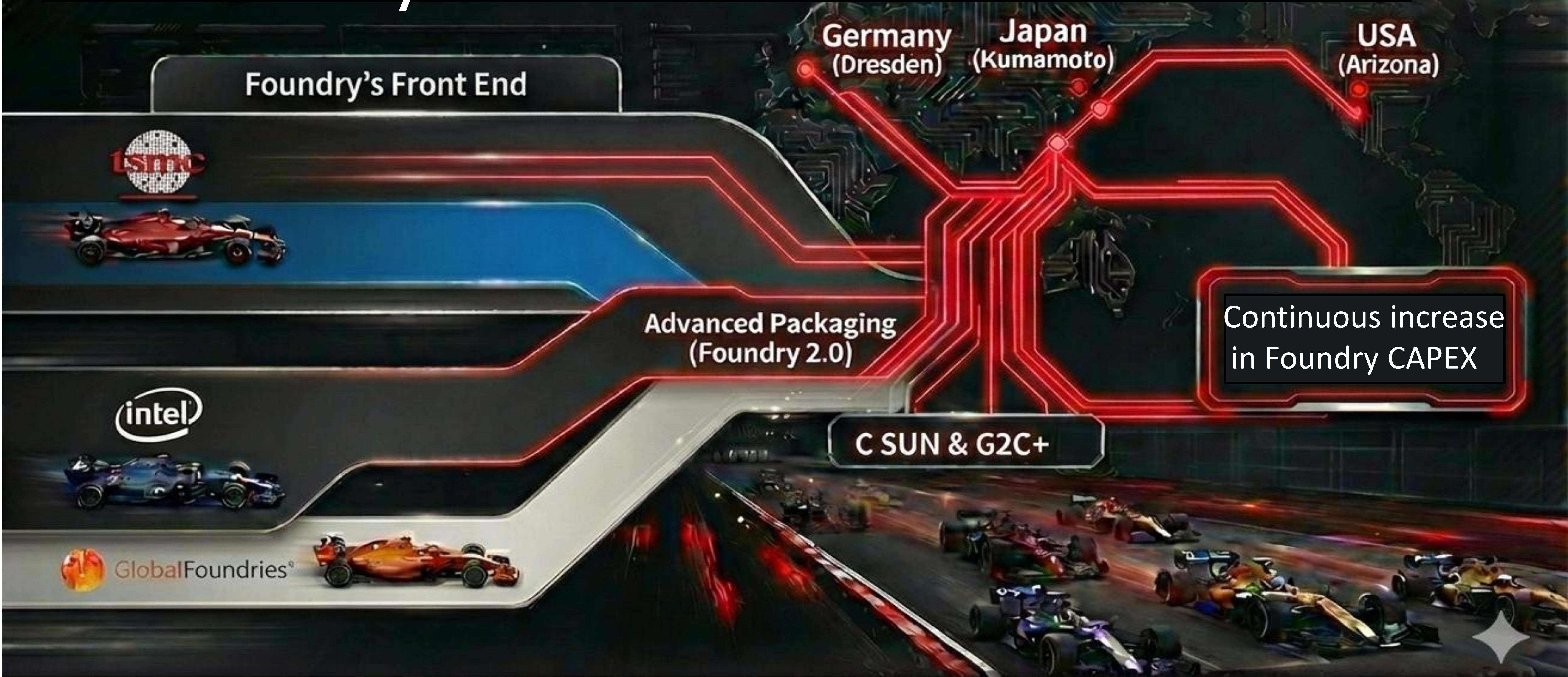
NT$ Million

Customers' CAPEX continues to flow in, providing sustainable momentum for future growth.

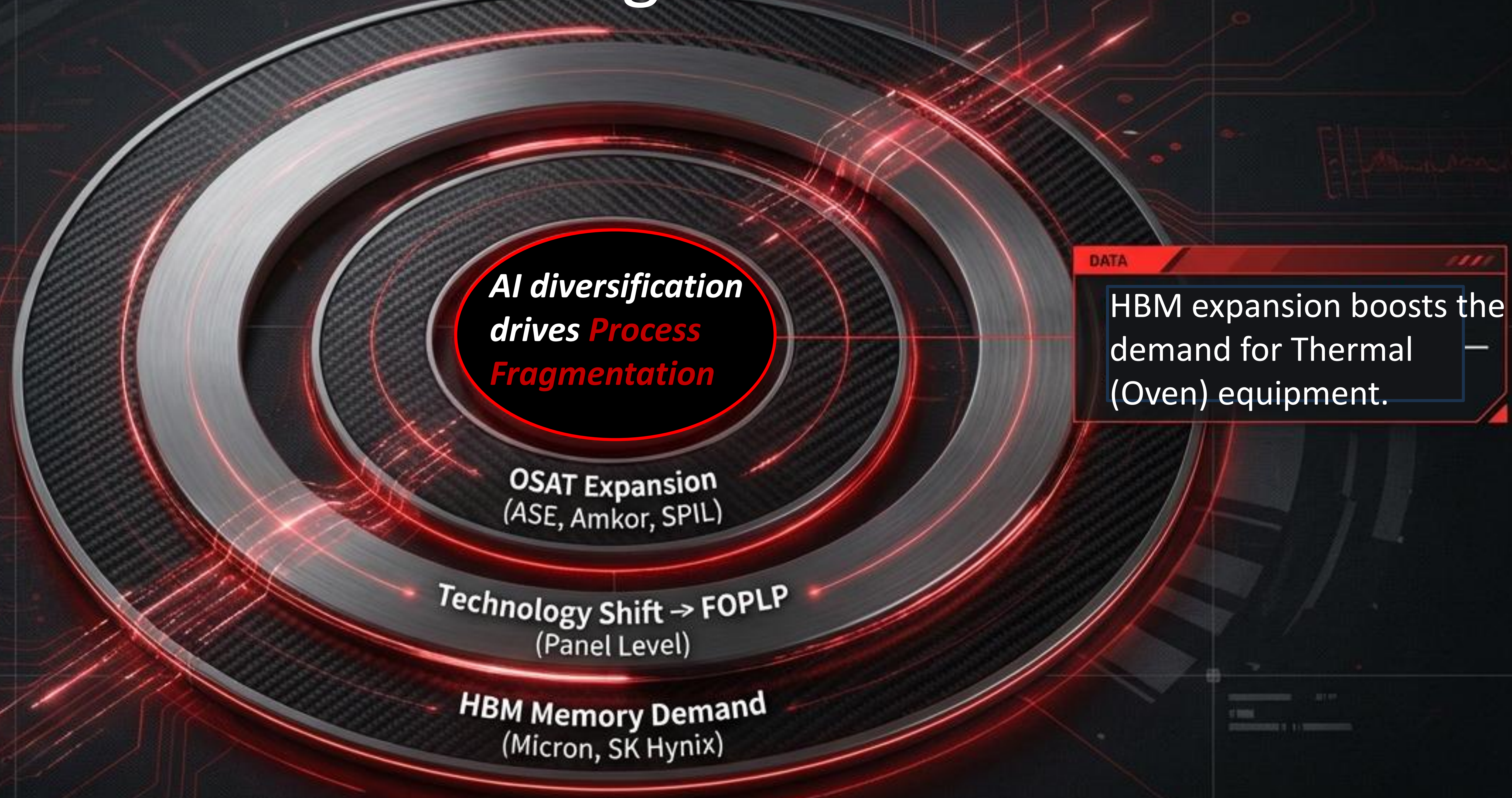
Dynamically aligning with customers' delivery schedules.


TSMC, intel, GF
FOUNDRY ACCESS TRACK
OSAT
ACCESS TRACK
AI SUBSTRATE & HDI
ACCESS TRACK
TSMC | Intel | GF
OSAT
AI substrate & HDI
SoIC
InFO
EMIB
X-CUBE
WMCM
Adv. PLP
SoIC
InFO
FlipChip
FoCoS
FoPLP
CoWoS
CoWoS
CoWoP
CoWoP
CoWoS
ABF
SAP
HDI
mSAP
mSAP
Advanced Packaging
GRAND CIRCUIT
GRAND CIRCUIT
GRAND CIRCUIT

Growth Engine I: Following the Leader - Foundry 2.0 Glocalization



Growth Engine II: AI Chip Diversification drives Process Fragmentation



HBM expansion boosts the demand for Thermal (Oven) equipment.

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Growth Engine III: High-End PCB Product Mix Upgrade & Regional Shift

Optimizing product mix drives ASP enhancement, continuously improving profitability structure.

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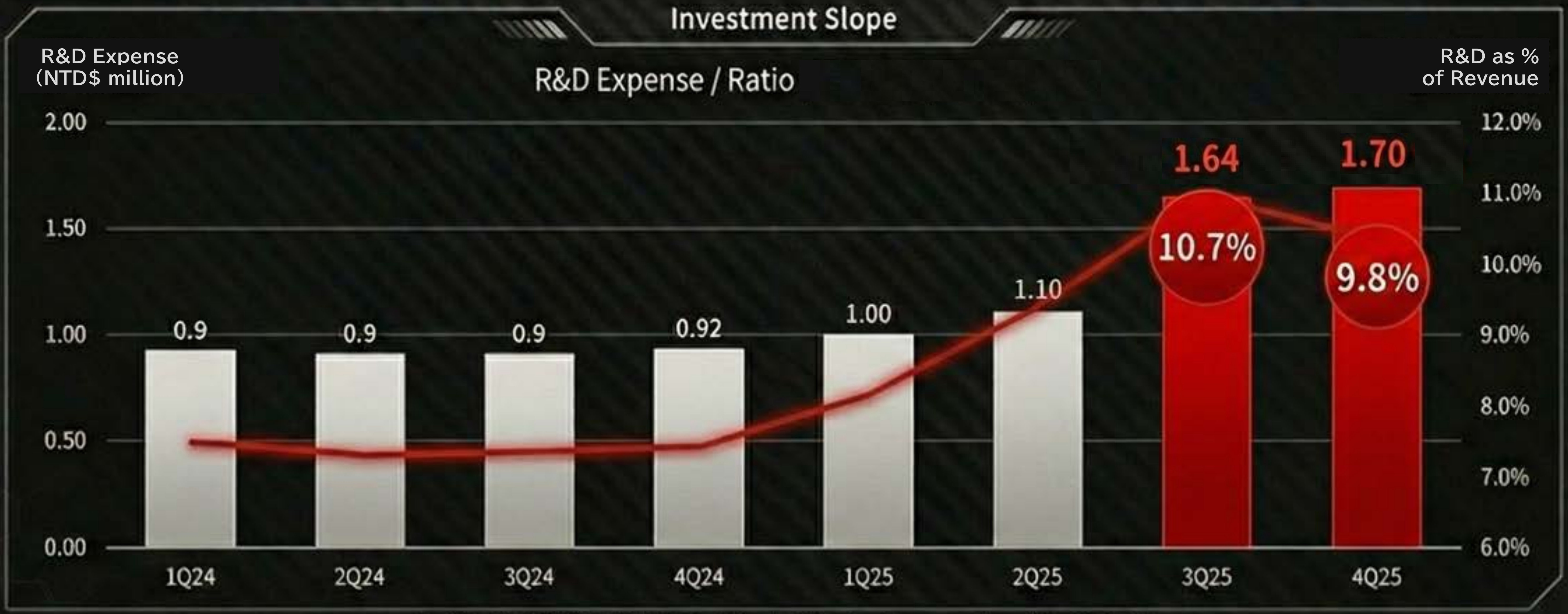
R&D Resource Allocation & Tech Upgrade

Next-Gen Processes & Equipment Upgrade for Advanced Packaging Supply Chain



Investments during the tech upgrade phase will support growth momentum for the next 3-5 years.

Technology Roadmap: Full Spectrum Coverage

Not only capitalizing on current advanced packaging dividends, but already positioned for future new process demands over the next 3 years.

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Building the Nest: R&D Center & Global Expansion

NT$ 1.48 Billion

Heavy investment in plants and facilities to ensure capacity security for the next 5 years.

ROBOTO MONO | Noto Sans TC Medium | TELEMETRY | STATUS: OPTIMAL | PROCESS LOOP: ACT2VE | TEMP: 400°C

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F1 ADVANCED PACKAGING GRAND PRIX
Foundry Main Track
CoWoS / SoIC / WMCM
tsmc
OSAT Track
PLP / oS / Bumping / CoW / EMIB
ASE
PTI
AI Substrate & HDI Track
IC Substrate / HDI
Unimicron
Zhen Ding
G2C+